PCN Number:		20150209000					PCN D	ate:	2/10/2015					
Title: Qualification family of dev					aiwan for Al	ter	nate A	SSE	embly sit	e wit	:h ne	w BOM f	or the	DP83848
Customer Contact:		PCI	N Ma	Manager Dept: Quality Services			!S							
Proposed 1st Ship Da			ite:	(5/10/2015 Estimated Sample Avai			vail	ability:	02/2	28/2015			
Change Type:														
Assembly Site				Assembly Process			\boxtimes	Assembly Materials						
Design				Electrical Specification				Mechanical Specification						
Test Site					Packing/Shipping/Labeling			Test Process						
■ Wafer Bump Site					Wafer Bump Material				Wafer Bump Process					
Wafer Fab Site					Wafer Fab Materials			Wafer Fab Process						
Part number change							•							
PCN Details														

Description of Change:

Texas Instruments is pleased to announce the qualification of TI Taiwan as an alternate Assembly location for the family of DP83848 devices. BOM differences are noted below:

	TI Melaka	ASEK	TAI
Mount Compound	8001746	SID#1400013111	4211470
Mold Compound	8095183	SID#1800008161	4209640
Bond Wire	Au, 1.0 mils	Au, 1.0 mils	Cu, 0.8 mils
Composition/Diameter			
Lead Finish	Matte Sn	Matte Sn	NiPdAu

Upon expiry of this PCN TI will combine lead free solutions in a single standard part number, for example; <u>DP83848CVV/NOPB</u> - can ship with both Matte Sn and NiPdAu/Ag.

Example:

- Customer order for 7500units of **DP83848CVV/NOPB** with 2500 units SPQ (Standard Pack Quantity per Reel).
- TI can satisfy the above order in one of the following ways.
 - 3 Reels of NiPdAu finish. I.
 - II. 3 Reels of Matte Sn finish
 - III. 2 Reels of Matte Sn and 1 reel of NiPdAu finish.
 - IV. 2 Reels of NiPdAu and 1 reel of Matte Sn finish.

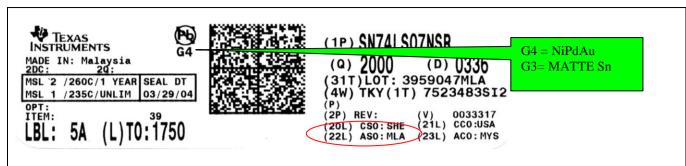
Reason for Change:

Continuity of Supply

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

None

Changes to product identification resulting from this PCN:					
Assembly Site					
TIEM-AT	Assembly Site Origin (22L)	ASO: CU6			
ASEK	Assembly Site Origin (22L)	ASO: ASF			
TI Taiwan	Assembly Site Origin (22L)	ASO: TAI			
Sample product shipping label (not actual product label)					



Topside Device marking:

Assembly site code for CU6= U Assembly site code for ASF= 7

Assembly site code for TAI= T

Product Affected

DP83848CVV/NOPB	DP83848IVV/NOPB	DP83848IVVX/S7002477	DP83848PVVX/NOPB	
DP83848CVVX/NOPB	DP83848IVVX/NOPB	DP83848PVV/NOPB		_



Qualification Report

DP83848 Product. LQFP package assembled at TITL Approved 12/16/2014

Product Attributes

Attributes	Qual Device: DP83848CVV/NOPB
Assembly Site	TAI/TITL
Package Family	LQFP
Flammability Rating	UL 94 V-0
Wafer Fab Site	MFAB
Wafer Fab Process	CMOS9T

- QBS: Qual By Similarity
- Qual Device DP83848CVV/NOPB is qualified at LEVEL3-260C

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

Туре	Test Name / Condition	Duration	Qual Device: DP83848CVV/NOPB	
PC	PreCon Level 3	Elec. Test at 25C	1/245/0	
HAST	Biased HAST, 130C/85%RH	96 hrs.	1/77/0	
AC	Autoclave 121C	196 hrs.	1/77/0	
TC	Temperature Cycle, -65/150C	1000 Cyc.	1/77/0	
TC	Post Temp Cycle Bond Pull	bond pull/shear	pass	
HTSL	High Temp Storage Bake 170C	420hrs	1/45/0	
MQ	Manufacturability (Assembly)	(Approved by A-T site)	1/Pass	

- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles
- Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com